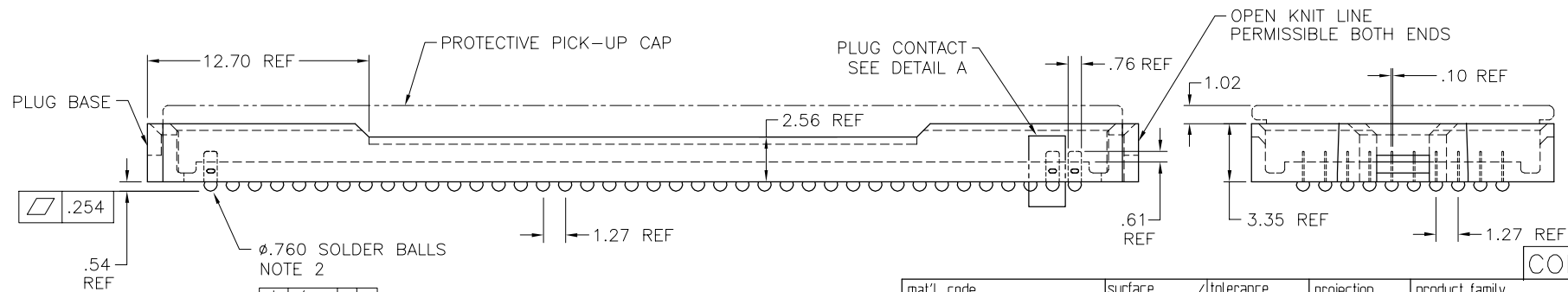
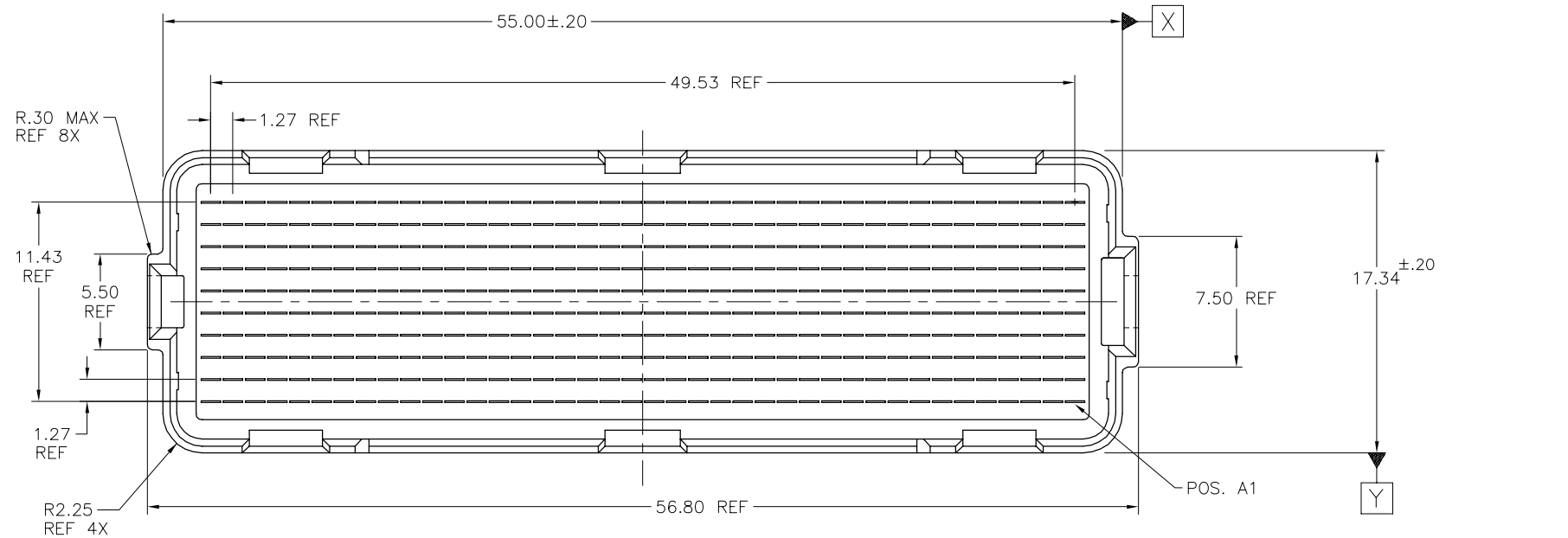

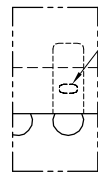




PRODUCT NUMBER
SEE TABLE

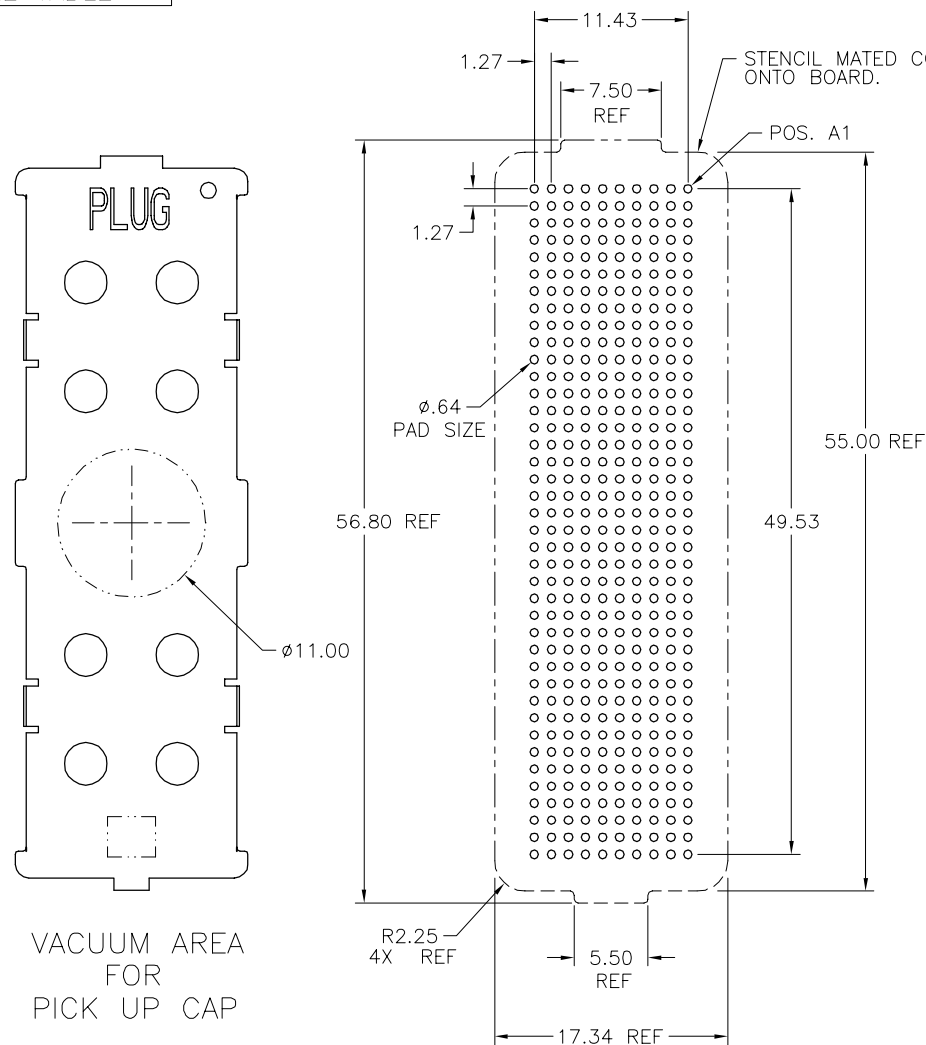
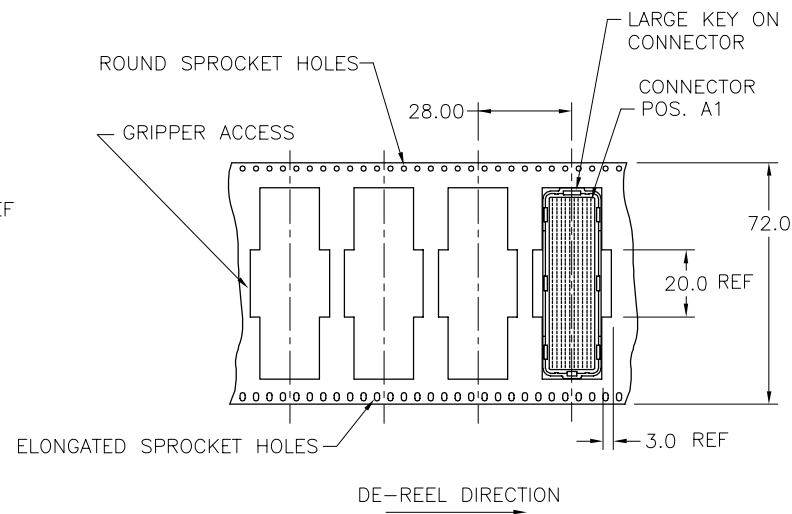


	$\varnothing.30$	X	Y
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




DETAIL A
SCALE 6:1

mat'l. code SEE NOTE 1				surface ASME Y14.5 ✓		tolerance ASME Y14.5		projection 		product family MEG-ARRAY									
lir		ecn no		dr		date		tolerances unless otherwise specified						title					
A		V05-0324		DAI		04/19/05		<div>angles</div> <div>lead</div>		X ±.3						<div>mm</div> <div>← — →</div>		0mm PLUG ASSY 10 x 40 = 400 POS.	
B		V06-0560		LP		2006/07/18				XX ±.13									
C		V08-0084		LP		2008-03-18				XXX ±.051									
								dr		D.INGRAM		8/24/04		<div>FCI</div> <div></div>		dwg no sheet 1 of 3 size 10043857 A4 type CUSTOMER Drawing			
						engr		D.HARPER		8/24/04									
						chr		D.HARPER		8/24/04									
						appd		D.HARPER		8/24/04									
sheet index		revision sheet		C		C		C											
				1		2		3											

PRODUCT NUMBER
 SEE TABLE

 BOARD PATTERN
 SCALE 2/1

 TAPE & REEL PACKAGING SCALE NONE
 PER EIA 481-3

CONFIDENTIAL

mat'l. code SEE NOTE 1				surface ASME Y14.5 ✓		tolerance ASME Y14.5		projection 		product family MEG-ARRAY			
ltr	ecn no	dr	date	tolerances unless otherwise specified				 scale 2:1		title			
c				angles		linear				0mm PLUG ASSY. 10x40= 400 POS.			
				0° ±2°									
				dr	D.INGRAM	8/24/04				dwg no		sheet 2 of	size
				engr	D.HARPER	8/24/04				10043857		A4	
				chr	D.HARPER	8/24/04							
				appd	D.HARPER	8/24/04				type CUSTOMER Drawing			
sheet index		revision sheet											

PRODUCT NUMBER	PICK-UP CAP	CONTACT PLATING	SOLDER BALL
10043857-102	YES	30u"(0.76um) Au OVER Ni	SnPb
10043857-102LF			SnAgCu LEAD FREE ⑥⑦
10043857-202	YES	SEE MATED HEIGHT TABLE (BELOW)	SnPb
10043857-202LF			SnAgCu LEAD FREE ⑥⑦

NOTES:

①. MAT'L:

HOUSING: LCP
CONTACT: COPPER ALLOY

PLATING:

CONTACT: (SEE TABLE ON SHEET3)
SOLDER BALL: (SEE TABLE ON SHEET3)
EUTECTIC SnPb OR LEAD FREE
95.5Sn/4Ag/0.5Cu

②. SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.

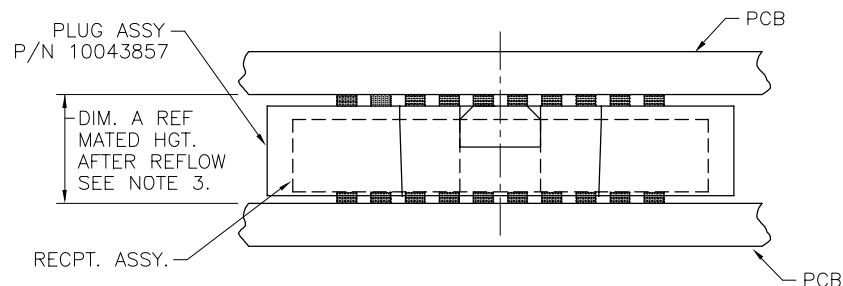
③. MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE.

④. PLATING FOR INDICATED -2XX SERIES PART NOS. MEETS THE REQUIREMENTS OF NORTEL NPS25298-2 (CENTRAL OFFICE ENVIRONMENT, 25 YEAR LIFE EXPECTANCY).

⑤. PLATING FOR INDICATED -2XX SERIES PART NOS. IS Au OVER Ni WITH SPECIAL CONTACT GEOMETRY TO MEET REQUIREMENTS OF TELCORDIA GR-1217-CORE: CENTRAL OFFICE ENVIRONMENT.

⑥. FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION

⑦. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION



MATED HEIGHT TABLE		
DIM. A	RECPT. ASSY. P/N	-2XX PLATING
4.0	74221	SEE NOTE 4
6.0	74388	SEE NOTE 5
8.0	74390	SEE NOTE 5

MATED HEIGHT AFTER REFLOW IS BASED ON ϕ .64mm PAD (METAL-DEFINED) AND .13mm SOLDER PASTE STENCIL THICKNESS. SEE NOTE 3.

END VIEW - MATED CONNECTORS SCALE NONE

CONFIDENTIAL

mat'l. code SEE NOTE 1				surface ASME Y14.5 ✓	tolerance ASME Y14.5	projection 	product family MEG-ARRAY	
ltr	ecr no	dr	date	tolerances unless otherwise specified			title	
c				angles	linear		0mm PLUG ASSY. 10x40= 400 POS.	
				0° ±2'	XXX ±.051	scale 2:1	dwg no	
				dr	D.INGRAM	8/24/04	sheet 3 of	
				engr	D.HARPER	8/24/04	10043857	
				chr	D.HARPER	8/24/04	type	
				appd	D.HARPER	8/24/04	CUSTOMER Drawing	
sheet	revision							
index	sheet							

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[FCI / Amphenol:](#)

[10043857-292LF](#) [10043857-292](#)